DGG OR DL PACKAGE

(TOP VIEW)

SCES024C - JULY 1995 - REVISED FEBRUARY 1999

- **Member of the Texas Instruments** Widebus™ Family
- **EPIC** ™ (Enhanced-Performance Implanted **CMOS) Submicron Process**
- **UBT**<sup>™</sup> (Universal Bus Transceiver) **Combines D-Type Latches and D-Type** Flip-Flops for Operation in Transparent, Latched, or Clocked Mode
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

#### description

This 18-bit universal bus transceiver is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

#### 56 GND OEAB [ 55 CLKAB LEAB 2 A1 🛮 3 54**∏** B1 GND ∏4 53 GND A2 🛮 5 52 B2 A3 🛮 6 51 B3 50 [] V<sub>CC</sub> V<sub>CC</sub> ∏7 A4 🛮 8 49∏ B4 A5 🛮 9 48 B5 A6 🛮 10 47 ∏ B6 GND [ 46 GND 11 45 B7 А7 П 12 A8 🛮 13 44 | B8 43**∏** B9 A9 🛮 14 A10 🛮 15 42 B10 A11 16 41 **∏** B11 A12 **∏**17 40 **∏** B12 GND [ 18 39 GND A13 **∏**19 38 **∏** B13 A14 20 37 B14 A15 🛮 21 36 B15 V<sub>CC</sub> 122 35 V<sub>CC</sub> A16 23 34 🛮 B16 A17 124 33 B17 GND ∏25 32 **∏** GND A18 **[**] 26 31 **∏** B18 OEBA 27 30 CLKBA

29 **∏** GND

LEBA 28

Data flow for B to A is similar to that of A to B, but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and OEBA is active low).

To ensure the high-impedance state during power up or power down, OEBA should be tied to V<sub>CC</sub> through a pullup resistor and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16501 is characterized for operation from -40°C to 85°C.



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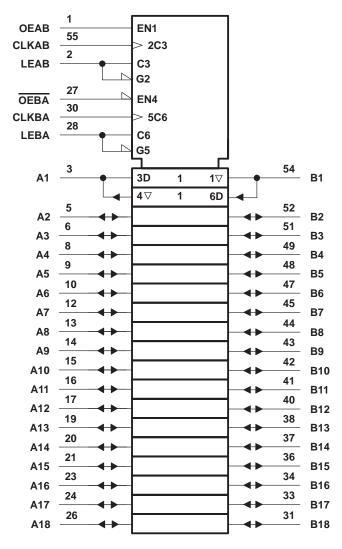


#### **FUNCTION TABLE**†

	INPUTS					
OEAB	LEAB	CLKAB	Α	В		
L	Х	Х	Х	Z		
Н	Н	Χ	L	L		
Н	Н	Χ	Н	Н		
Н	L	$\uparrow$	L	L		
Н	L	$\uparrow$	Н	Н		
Н	L	L or H	Χ	В <sub>0</sub> ‡		

<sup>†</sup>A-to-B data flow is shown: B-to-A flow is similar, but uses OEBA, LEBA, and CLKBA.

### logic symbol§

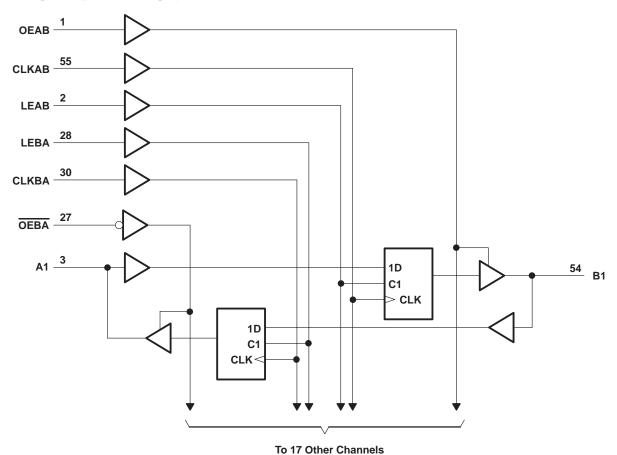


<sup>§</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



<sup>‡</sup>Output level before the indicated steady-state input conditions were established, provided that CLKAB is high before LEAB goes low

#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> : Except I/O ports (see Note 1)	
I/O ports (see Notes 1 and 2)	
Output voltage range, VO (see Notes 1 and 2)	
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG package	le 81°C/W
DL package	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. This value is limited to 4.6 V maximum.
  - 3. The package thermal impedance is calculated in accordance with JESD 51.



## **SN74ALVCH16501 18-BIT UNIVERSAL BUS TRANSCEIVER** WITH 3-STATE OUTPUTS SCES024C – JULY 1995 – REVISED FEBRUARY 1999

#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		1.65	3.6	V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V <sub>CC</sub>			
$V_{IH}$	<b>-</b>	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>		
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V	
	V	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	1	
٧ı	Input voltage		0	Vcc	V	
٧o	Output voltage		0	Vcc	V	
		V <sub>CC</sub> = 1.65 V		-4	m ^	
1	High-level output current	V <sub>CC</sub> = 2.3 V		-12		
ЮН		V <sub>CC</sub> = 2.7 V		-12	mA	
		V <sub>CC</sub> = 3 V		-24		
		V <sub>CC</sub> = 1.65 V		4		
lOL	Low lovel output ourrent	V <sub>CC</sub> = 2.3 V		12		
	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA	
	V <sub>CC</sub> = 3 V			24		
Δt/Δν	Input transition rise or fall rate	•		10	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAI	RAMETER	TEST C	ONDITIONS	vcc	MIN	TYP†	MAX	UNIT	
		I <sub>OH</sub> = -100 μA		1.65 V to 3.6 V	V <sub>CC</sub> -0.	.2			
	$I_{OH} = -4 \text{ mA}$		1.65 V	1.2					
	I <sub>OH</sub> = -6 mA	2.3 V	2						
Vон				2.3 V	1.7			V	
		I <sub>OH</sub> = -12 mA		2.7 V	2.2				
				3 V	2.4				
		$I_{OH} = -24 \text{ mA}$		3 V	2				
		I <sub>OL</sub> = 100 μA		1.65 V to 3.6 V			0.2		
		I <sub>OL</sub> = 4 mA		1.65 V			0.45		
V/01		I <sub>OL</sub> = 6 mA	2.3 V			0.4	V		
VOL	VOL	I <sub>OL</sub> = 12 mA		2.3 V			0.7	V	
	IOL = 12 IIIA	2.7 V			0.4				
		I <sub>OL</sub> = 24 mA	3 V			0.55			
IJ		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ	
		V <sub>I</sub> = 0.58 V	1.65 V	25					
		V <sub>I</sub> = 1.07 V	1.65 V	-25					
		V <sub>I</sub> = 0.7 V	2.3 V	45					
I <sub>I</sub> (hold)		V <sub>I</sub> = 1.7 V	2.3 V	-45			μΑ		
((Tota)		V <sub>I</sub> = 0.8 V		3 V	75				
		V <sub>I</sub> = 2 V	3 V	-75					
		$V_{I} = 0 \text{ to } 3.6 \text{ V}^{\ddagger}$		3.6 V			±500		
loz§		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ	
ICC		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ	
∆lcc	-	One input at V <sub>CC</sub> – 0.6 V,	Other inputs at $V_{\hbox{\footnotesize CC}}$ or GND	3 V to 3.6 V			750	μΑ	
Ci	Control inputs	$V_I = V_{CC}$ or GND		3.3 V		4		pF	
C <sub>io</sub>	A or B ports	$V_O = V_{CC}$ or GND		3.3 V		8		pF	

#### timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

				V <sub>CC</sub> =	1.8 V	V <sub>CC</sub> =	2.5 V 2 V	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> =	3.3 V 3 V	UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
fclock	f <sub>clock</sub> Clock frequency			¶		150		150		150	MHz		
	tw Pulse duration	LE high		¶		3.3		3.3		3.3		ns	
t <sub>W</sub>	Puise duration	CLK high or low	1	¶		3.3		3.3		3.3		115	
		Data before CL	K↑	¶		2.2		2.1		1.7			
t <sub>su</sub>	Setup time	Data	CLK high	¶		1.9		1.6		1.5		ns	
	before LE↓	CLK low	¶		1.3		1.1		1				
4.	t <sub>h</sub> Hold time	Data after CLK↑		¶		0.6		0.6		0.7			
<sup>t</sup> h		Data after LE↓	CLK high or low	¶		1.4		1.7		1.4		ns	

<sup>¶</sup> This information was not available at the time of publication.



<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C. ‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

 $<sup>\</sup>$  For I/O ports, the parameter IOZ includes the input leakage current.

## SN74ALVCH16501 **18-BIT UNIVERSAL BUS TRANSCEIVER** WITH 3-STATE OUTPUTS SCES024C – JULY 1995 – REVISED FEBRUARY 1999

# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC =	1.8 V	V <sub>CC</sub> =	2.5 V 2 V	VCC =	2.7 V	V <sub>CC</sub> =	3.3 V 3 V	UNIT
	(INFOT)	(001701)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			†		150		150		150		MHz
	A or B	B or A		†	1	4.8		4.5	1	3.9	
t <sub>pd</sub>	LE	A or B		†	1.1	5.7		5.3	1.3	4.6	ns
	CLK	AUID		†	1.2	6.1		5.6	1.4	4.9	
t <sub>en</sub>	OEAB	В		†	1	5.8		5.3	1	4.6	ns
t <sub>dis</sub>	OEAB	В		†	1.5	6.2		5.7	1.4	5	ns
t <sub>en</sub>	OEBA	Α		†	1.3	6.3		6	1.1	5	ns
t <sub>dis</sub>	OEBA	Α		†	1.3	5.3		4.6	1.3	4.2	ns

<sup>†</sup> This information was not available at the time of publication.

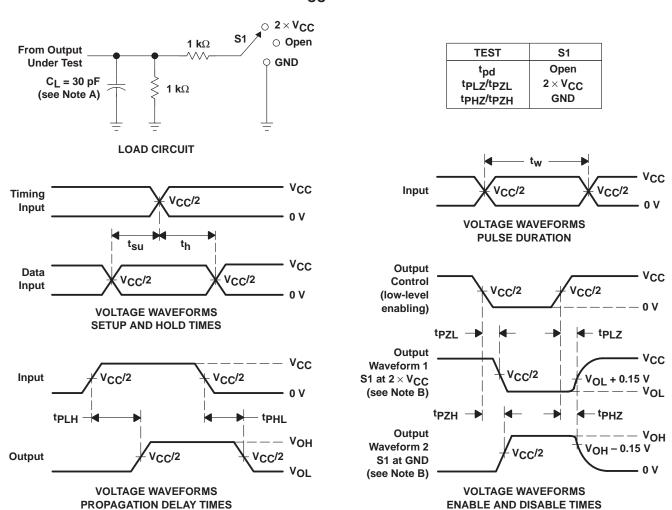
### operating characteristics, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT	
		TEST CONDITIONS	TYP	TYP	TYP	ONIT	
<u> </u>	Power dissipation	Outputs enabled	C 50 pF	†	44	54	pF
C <sub>pd</sub>	capacitance	Outputs disabled	$C_L = 50 \text{ pF},  f = 10 \text{ MHz}$	†	6	6	рг

<sup>†</sup> This information was not available at the time of publication.



# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V}$

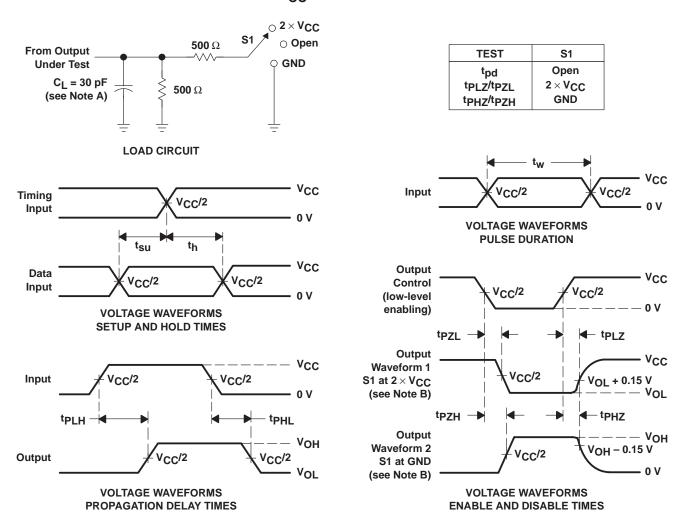


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2$  ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpLz and tpHz are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

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# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



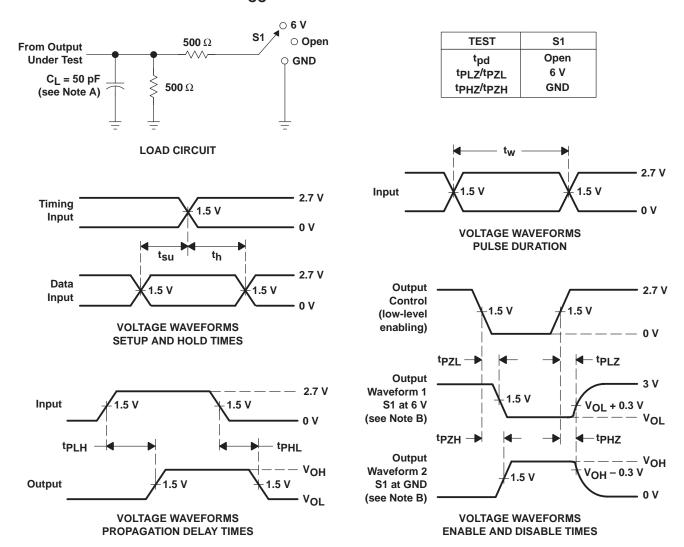
NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50~\Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.7 \text{ V}$ AND 3.3 V $\pm$ 0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 3. Load Circuit and Voltage Waveforms

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